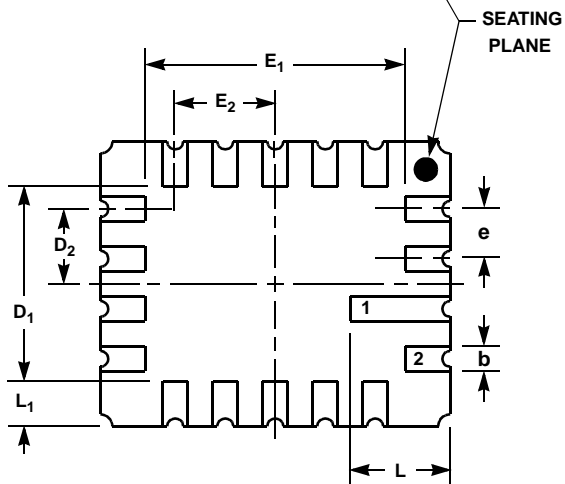
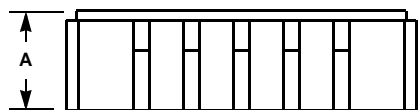
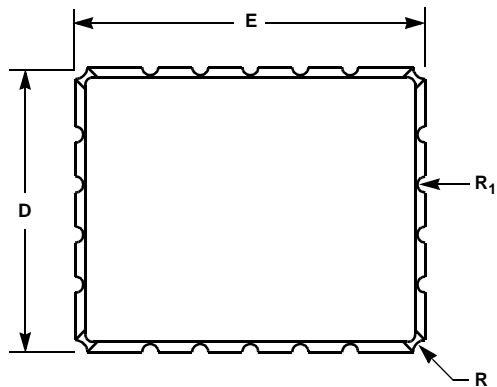


**18 Pin CLCC**  
**18 PIN CERAMIC LEADLESS CHIP CARRIER**



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.09	0.112	2.34	2.84	-
b	0.02	0.030	0.51	0.76	-
D	0.27	0.295	6.99	7.49	-
D <sub>1</sub>	0.17	0.215	4.45	5.46	-
D <sub>2</sub>	0.07	0.080	1.78	2.03	-
E	0.34	0.360	8.64	9.14	-
E <sub>1</sub>	0.24	0.280	6.10	7.11	-
E <sub>2</sub>	0.09	0.105	2.42	2.66	-
e	0.050 BSC		1.27 BS		-
L	0.08	0.115	2.16	2.92	-
L <sub>1</sub>	0.03	0.055	0.89	1.39	-
R	0.00	0.017	0.18	0.43	4
R <sub>1</sub>	0.00	0.013	0.08	0.33	4

**NOTES:**

1. No current JEDEC outline for this package.
2. All exposed metallized areas shall be plated with a minimum of 50 microinches of gold over nickel unless otherwise stated.
3. Metallized castellations shall be connected to the seating plane and extend upward toward top of package.
4. Corner shape (notch, radius, square, etc.) may vary at the manufacturer's option.
5. Unless otherwise specified, a minimum clearance of 0.010 inches (0.25mm) shall be maintained between all metallized areas.
6. Controlling dimension: Inch.
7. Revision 1 dated 6-93.